

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

SSOP

(printed on: 2020-07-11 16:25:39)

**TOTAL MASS (g) : 0.080291**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001807	1000000	22505.6171875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.029933	975000	372806.09375		
		Iron (Fe)	7439-89-6	0.000737	24000	9179.10351562		
		Phosphorus (P)	7723-14-0	0.000009	300	112.092170715		
		Zinc (Zn)	7440-66-6	0.000021	700	261.548370361		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.030700</b>	<b>1000000</b>	<b>382358.84375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002272	1000000	28298.0429688		
		<b>External Plating Total:</b>				<b>0.002272</b>	<b>1000000</b>	<b>28298.0429688</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000246	1000000	3063.8527832		
<b>Internal Plating Total:</b>				<b>0.000246</b>	<b>1000000</b>	<b>3063.8527832</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000643	750000	8008.36279297		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000214	250000	2665.30273438		
<b>Die Attach Total:</b>				<b>0.000857</b>	<b>1000000</b>	<b>10673.6650391</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006623	150000	82487.3828125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.036203	820000	450896.96875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.001104	25000	13749.9726562		
		Carbon Black (C)	1333-86-4	0.000221	5000	2752.48535156		
		<b>Encapsulation Total:</b>				<b>0.044151</b>	<b>1000000</b>	<b>549886.8125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000258	1000000	3213.30859375		
					<b>TOTAL MASS (g) :</b>	<b>0.080291</b>		